
New vacuum coating technologies for metal strips and foils



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*AIMCAL WC&H Conference 2016 – Europe
30 May – 2 June, 2016, Dresden, Germany*

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1 Introduction

- Growing interest for metal strips and foils with special surface functions
- Call for very thin substrate materials for light-weight applications and saving resources
- Complex layer systems with special and high-quality properties needed
- Requirement for low cost coating technologies onto large areas
- Motivation to use PVD/PECVD processes:
 - Variety of layer materials available for deposition (metals, alloys, compounds, ...)
 - Very precise coating
 - Outstanding environmental compatibility of processes
 - Promising R&D results and first industrial applications
- Demands for new processes:
 - High-rate deposition but with excellent layer properties -> plasma assistance
 - adapted pre-treatment processes
 - active substrate cooling in vacuum during coating
- First industrial application in development, especially in the field of energy

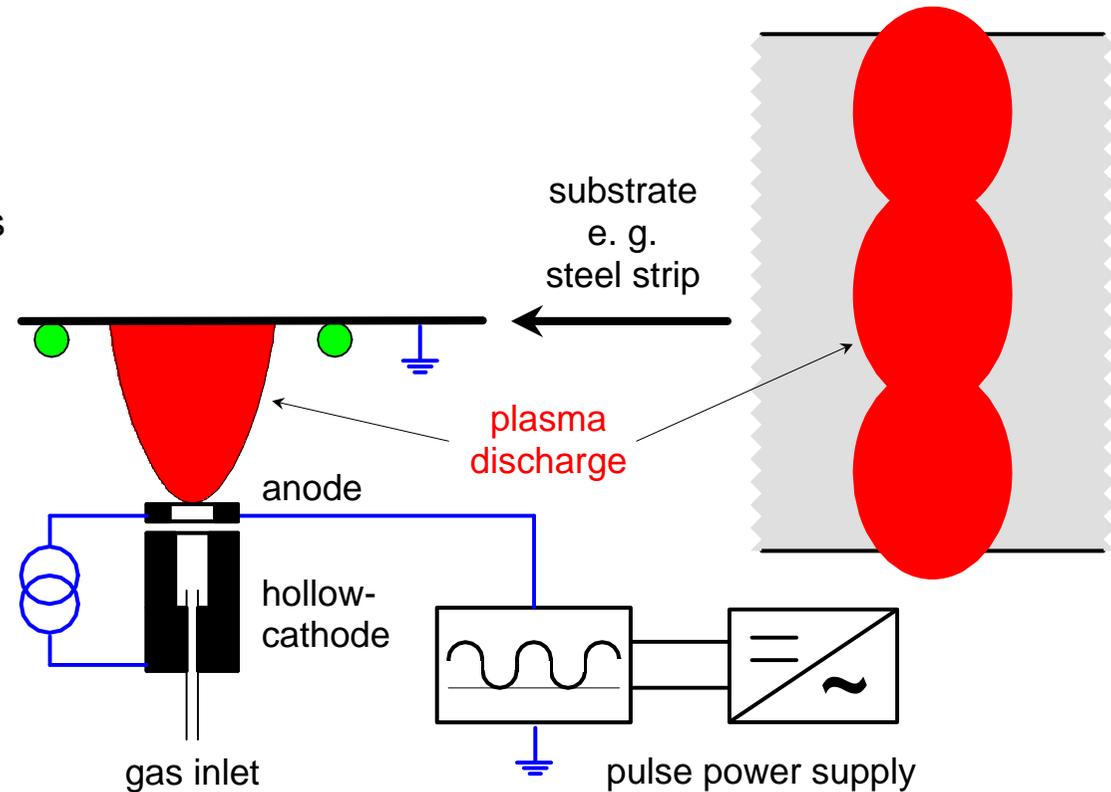
2 Vacuum in-line pre-treatment by hollow cathode sputter etching

Parameter for one etching station

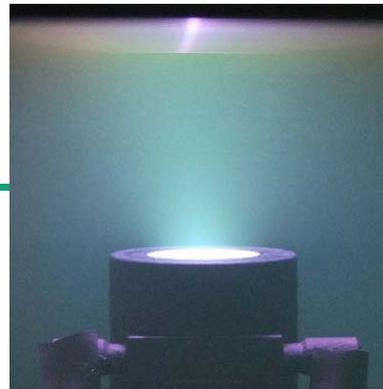
Power: 50 kW with 5 hollow cathodes
per 1 meter strip width

Etching rate: 5 nm at 1 m/s strip speed;
higher removal by
arranging some
stations

Frequency: 20 – 50 kHz (sine wave)
for arc depression

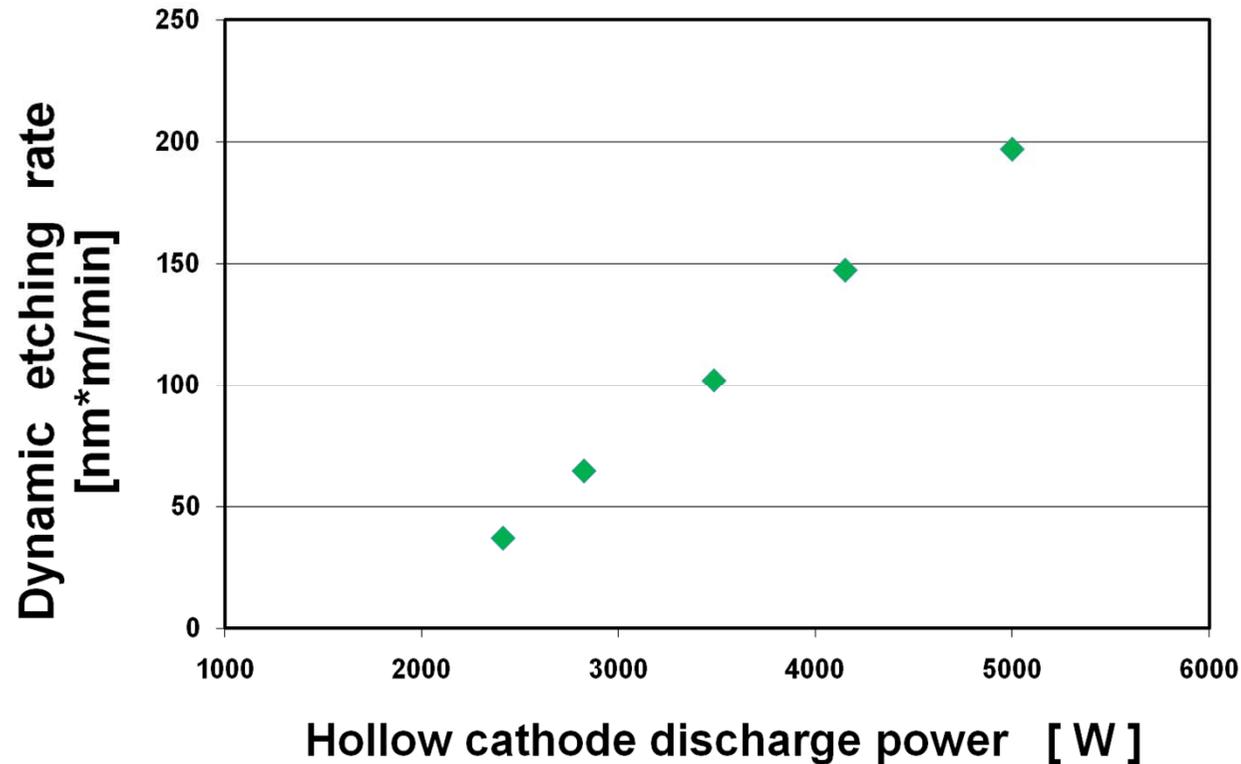


non magnetic and ferror-magnetic
metal strips with arbitrary thickness



2 Vacuum in-line pre-treatment by hollow cathode sputter etching

Dynamic etching rate of Cu strip



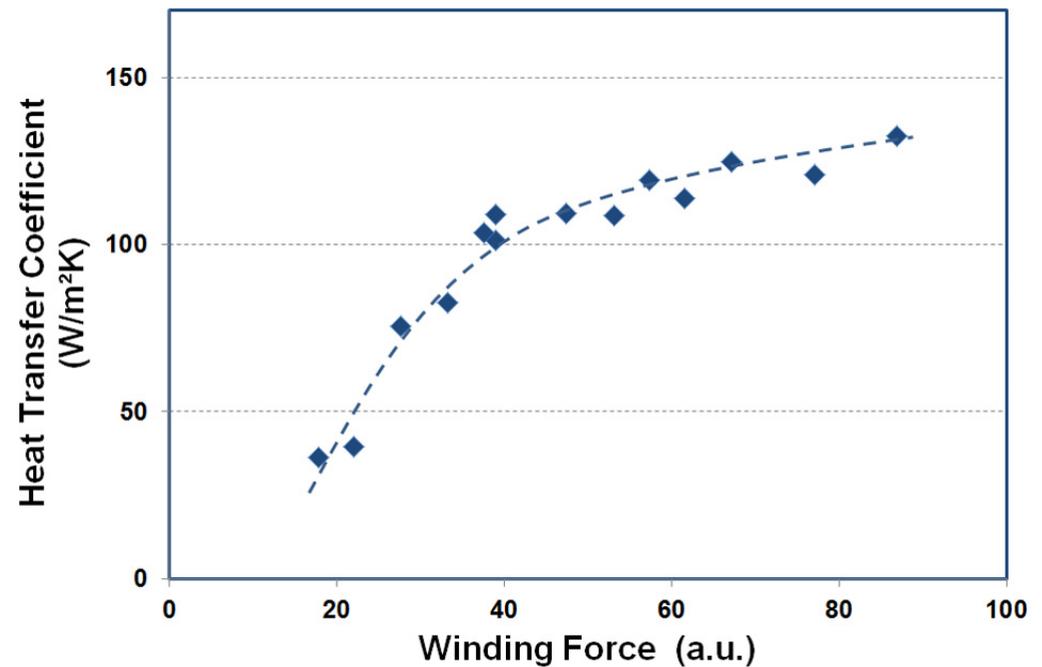
Etching rate depends on

- realized power in hollow cathode (discharge current \times discharge voltage) and
- Bias Voltage (pulse power supply, about 400 – 600 V)

Powerful plasma sources are needed \rightarrow Hollow cathode arc source

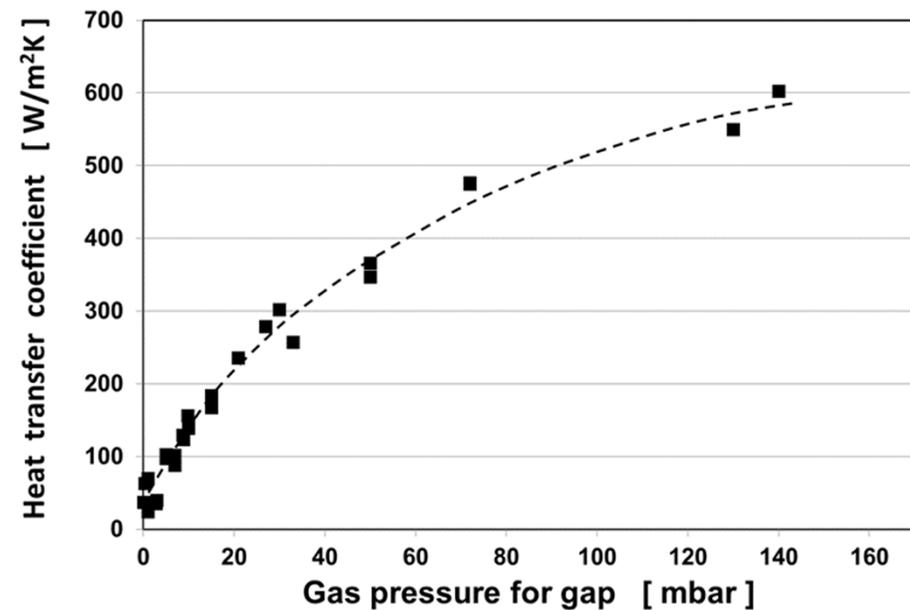
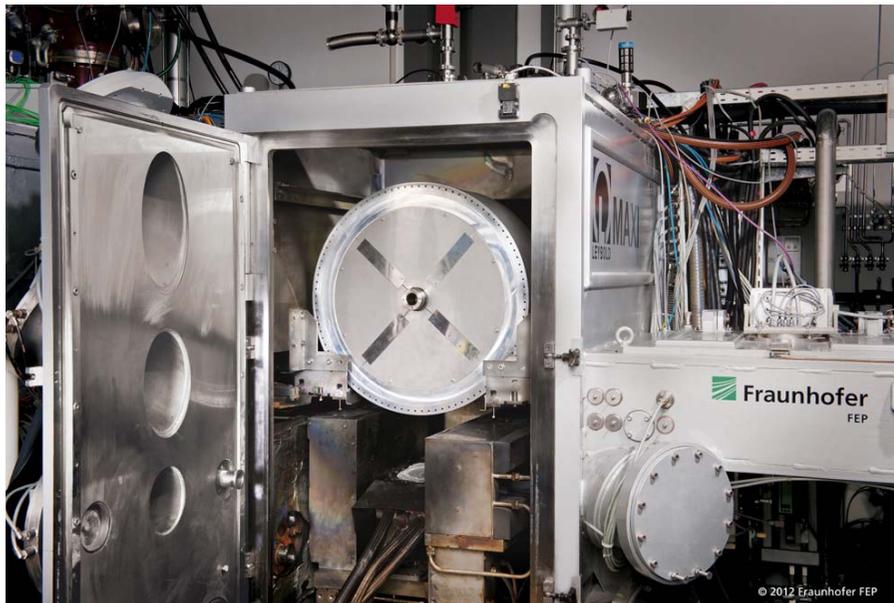
3 Substrate cooling in vacuum – Brush cooling

- Idea: realization of a large number of effective working contact points for heat transportation by brush arrangement
- Heat transmission coefficients of up to $150 \text{ W/m}^2\text{K}$ were reached with a static brush cooling device.



3 Substrate cooling in vacuum – Gas cooling drum

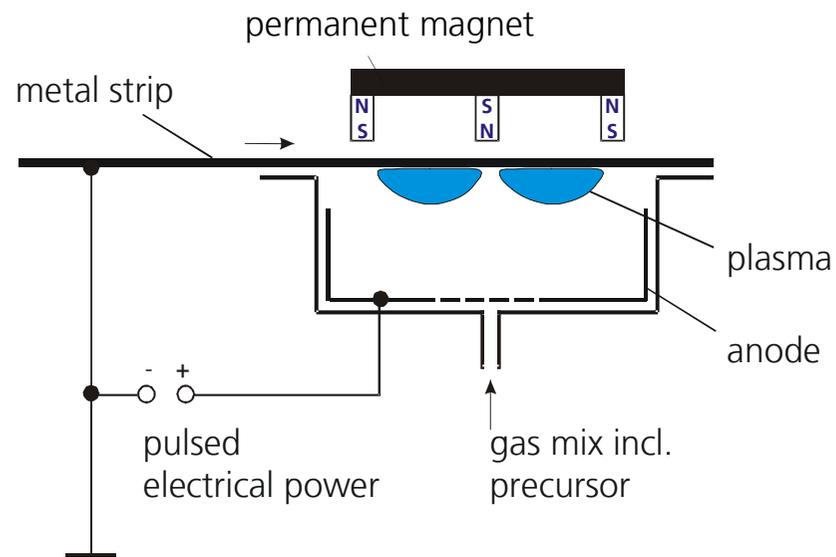
- Idea: realization of gas filled contact area for heat transportation between strip and cooling drum, meanwhile the requirements on the pressure for vacuum coating ($1 \cdot 10^{-4}$ mbar) were fulfilled.
- Heat transmission coefficients of up to $600 \text{ W/m}^2\text{K}$ were reached with a gas cooling drum. There are further potential for increasing of cooling effect.



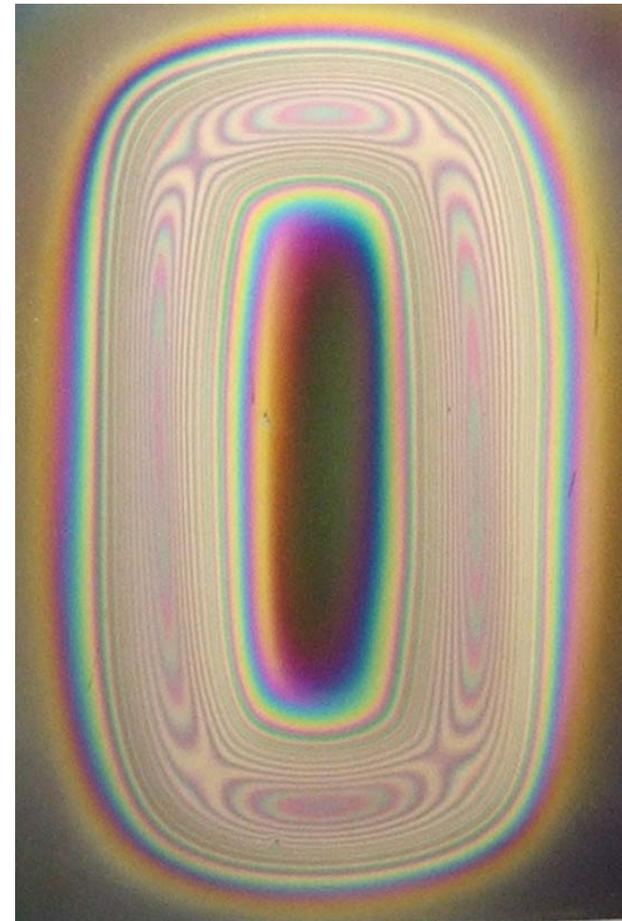
4 PECVD process for metal strips

Principle:

- magnetron discharge burning on the metal strip (= cathode)
- Metal strip at ground potential, encapsulated anode
- MF-pulsed glow discharge

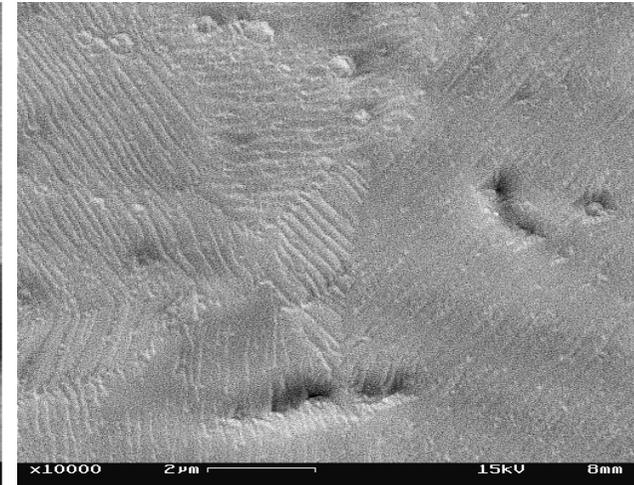
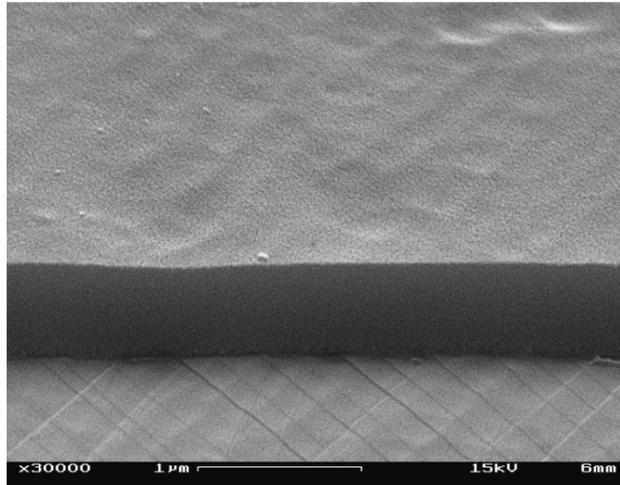
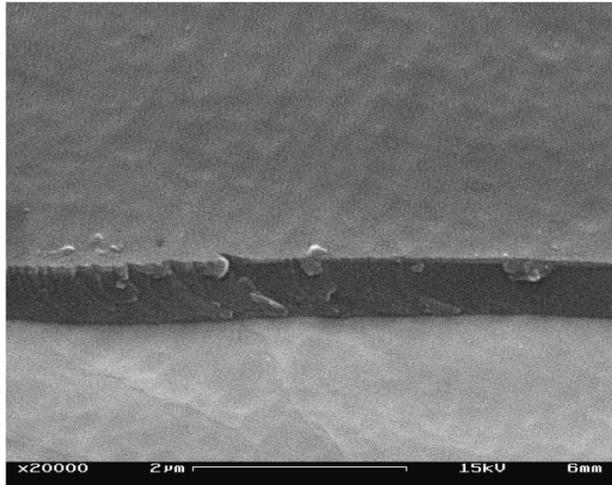


transparent
a-C:H:Si:O
coating deposited
onto a stationary
steel sheet,
precursor HMDSO



4 PECVD process for metal strips

Examples for coatings on metal strips



a-C:H

precursor: C_2H_2
dep. rate: 110 nm/s
thickness: 0,9 μm
hardness: 40 GPa

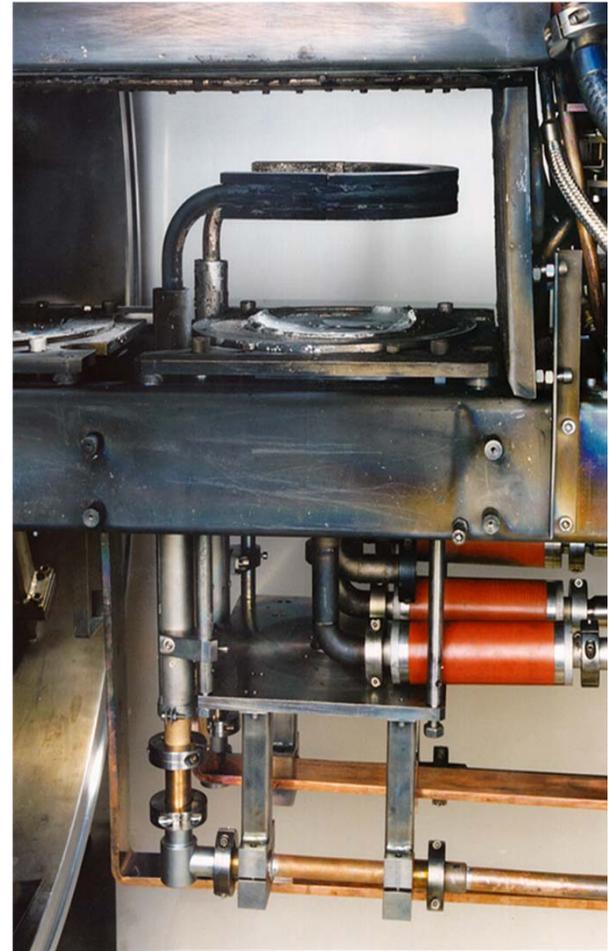
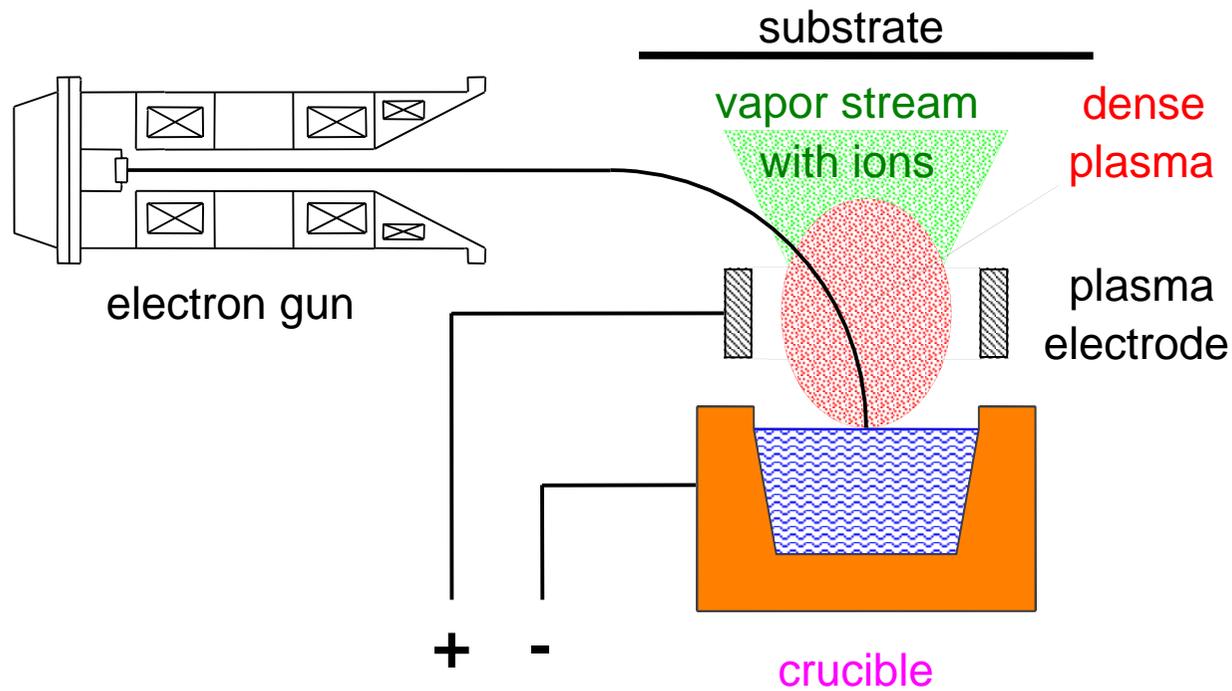
a-C:H:Si:O

precursor: HMDSO
dep. rate: 50 nm/s
thickness: 0,7 μm
hardness: 13 GPa
EDX: O/Si 1,0

a-Si:H

precursor: SiH_4
dep. rate: 3 nm/s
thickness: 1,6 μm

5 Plasma activated high-rate electron beam PVD Spotless arc Activated Deposition (SAD process)

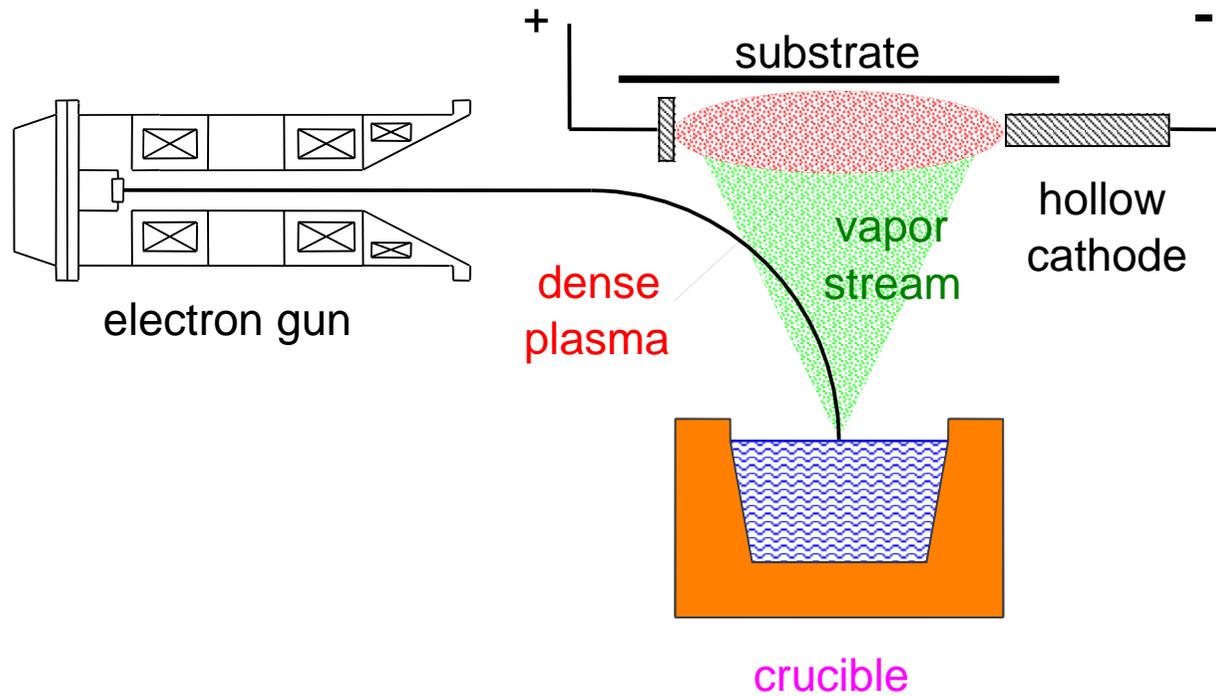


5 Plasma activated high-rate electron beam PVD Spotless arc Activated Deposition (SAD process)

- Plasma activated deposition of high melting metals (Ti, Zr, Cr, W, Mo, ...), alloys and compounds (Nitrides, Oxides, Carbides) e.g. TiN, TiC, TiO₂, WC, ZrN, ...
- High deposition rates onto large areas up to 2 μm/s for metals and alloys up to 200 nm/s for compounds
- High ion current density at the substrate (100 – 300 mA/cm²)
- Pure metal plasma (ionisation degree up to 60%)
- Dense layers without droplets
- Arrangement for large deposition width by deflection of electron beam and spotless arc (approved up to 600 mm)



5 Plasma activated high-rate electron beam PVD Hollow cathode arc Activated Deposition (HAD process)



5 Plasma activated high-rate electron beam PVD Hollow cathode arc Activated Deposition (HAD process)

- plasma activation for high-rate electron beam evaporation, especially of insulating and other compounds (SiO_x , Al_2O_3 , TiO_2 , TiN , CrN , ...) and C containing hard coatings
- high deposition rates onto large areas
e.g.:
50 ... 100 nm/s for Al_2O_3
100 ... 1 000 nm/s for SiO_x
- high ion current density at the substrate ($10 - 50 \text{ mA/cm}^2$)
- ionisation degree of the vapour up to 50%
- dense layers without droplets
- arrangement for large deposition width (proven up to 2 850 mm)



6 Application: Photo catalysis and photo wettability (TiO₂)

Crystalline (anatas) titanium dioxide shows special properties:

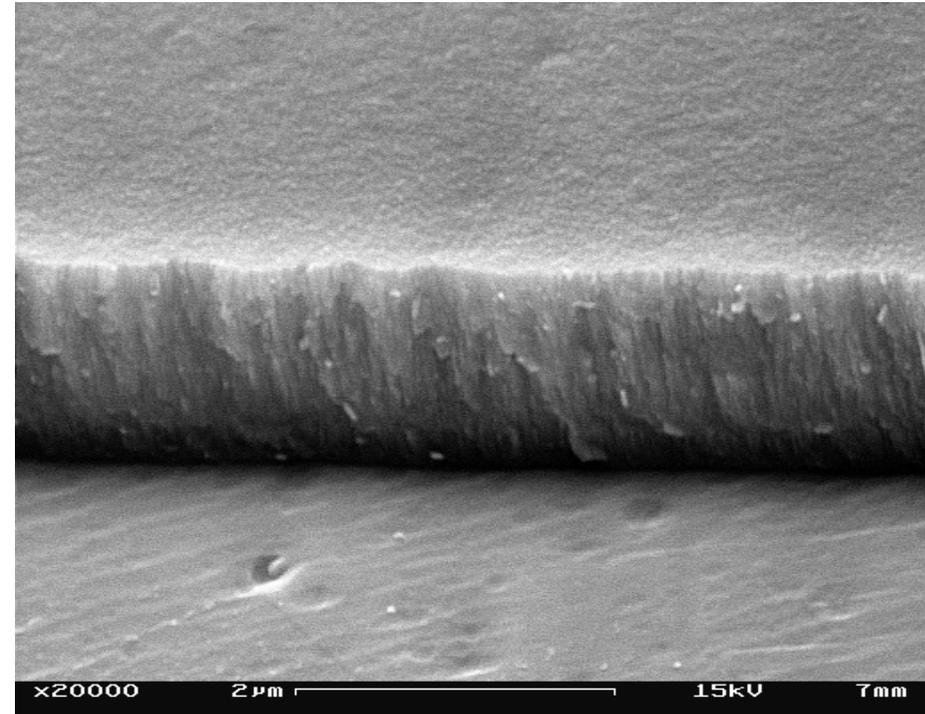
- Photo catalysis
 - Stimulation of oxidation and reduction processes after activation of the coating (Exposure with UV-A or sunlight)
 - Decomposition of organic and inorganic substances on the surface
- Photo wettability / hydrophilicity
 - degradation of the contact angle against water to below 10° after activation of the layer
 - formation of a closed water film on the surface
- High deposition rates up to 100 nm/s
- Dense layer structure and high hardness by plasma activated deposition



6 Application: Hard coatings (TiC / WC)

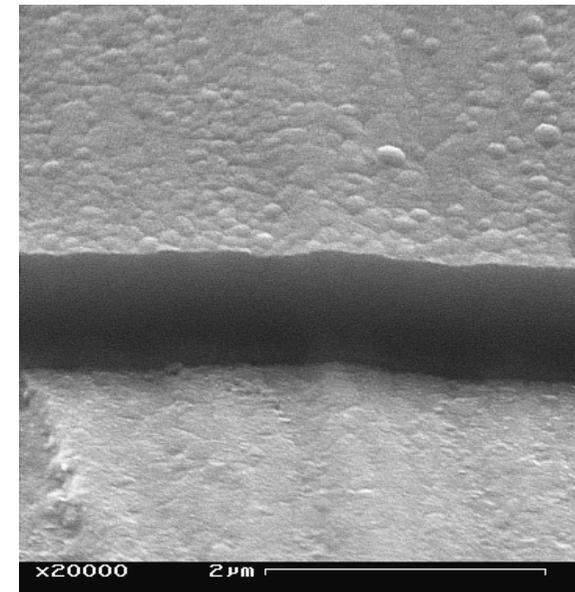
Reactive Deposition of TiC and WC onto large areas by SAD process:

- Electron beam evaporation of Ti or W in carbon containing atmosphere
- Deposition of TiC:
 - deposition rate up to 100 nm/s
 - hardness up to 33 GPa
- Deposition of WC:
 - deposition rate up to 200 nm/s
 - hardness up to 30 GPa
- Good layer adhesion



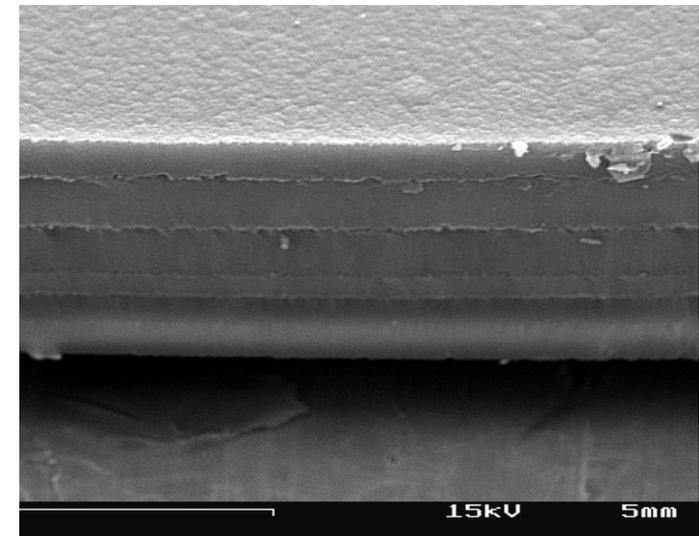
6 Application: Silicon oxide layers for transparent abrasion and corrosion resistance

- Deposition rate up to 150 nm/s
by plasma activated high-rate electron beam deposition (HAD process)
- High layer hardness (up to 15 GPa)
caused by high degree of ionization in vapor and enhanced substrate temperature (Si-rich SiO_x layers made by combination of PVD and CVD)
The layer hardness is higher than hardness of bulk SiO_2 material (10 GPa).
- High hardness caused by special nano composite material structure (nano crystalline Si could be detected in amorphous SiO_2 matrix by XRD)
- Low absorption ($k < 0.01$ @ 550 nm)
in the total hardness range from 5 to 15 GPa
- Good corrosion protection due to dense layer structure.



6 Application: Silicon oxide layers for isolating properties

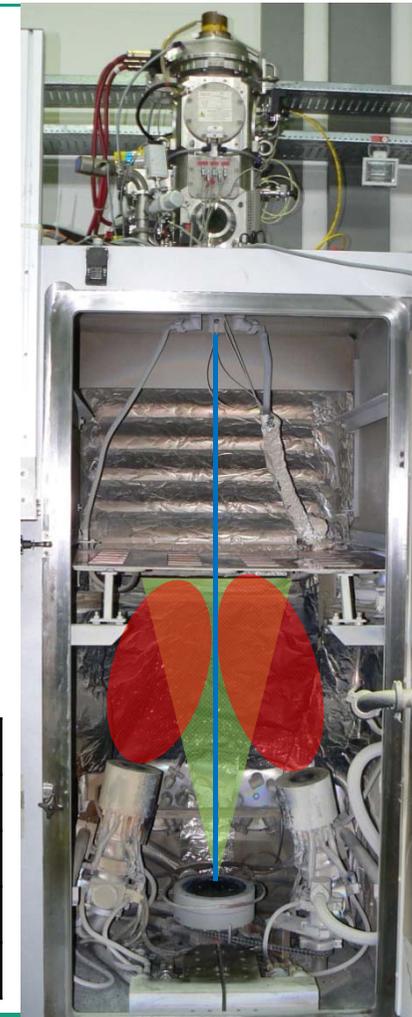
- Deposition of SiO_x based electrically insulating layers on metal strips and foils
 - layer thickness about $10\ \mu\text{m}$ without delaminating
 - brake down voltage of about a few $100\ \text{V}$ ($> 10\ \mu\text{m}$)
- Successful organic modification to reduce stress by introduction of a monomer in the plasma => combination of HAD + PECVD
- Isolating properties depend strongly from excellent surface quality of the substrate:
 - low roughness
 - extremely low surface defect density



6 Application: Silicon oxide layers in optical layer quality

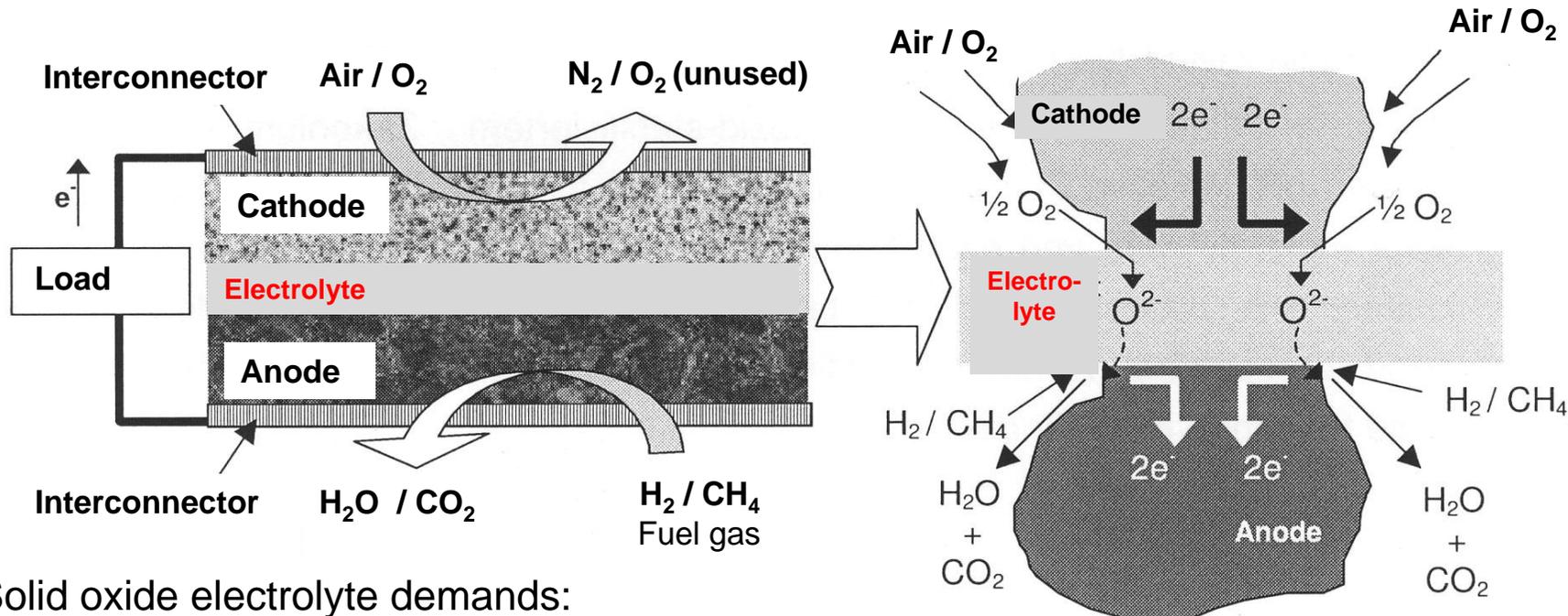
- Plasma-activated electron beam evaporation (HAD process)
 - electron beam evaporation of Silicon Dioxide
 - hollow cathode arc discharge in vapor/argon atmosphere
 - reactive processing in oxygen atmosphere
 - large distance between crucible and substrate (about 1 m) for excellent layer homogeneity
- Substrate: aluminum strip
 - strip width 300 mm
 - surface quality mirror finished
- Characteristic parameters for SiO_x layers deposited with large crucible-substrate distance

static rate	nm/s	10	20	50
dynamic rate	nm*m/min	400	800	2000
micro hardness	GPa	6	5	4
refractive index	n @ 550 nm	1.50	1.49	1.48
absorption	k @ 550 nm	1 x 10 ⁻³	5 x 10 ⁻⁴	5 x 10 ⁻⁴



6 Application: Zirconium oxide coatings for fuel cells

Principle of a High-temperature (600 ... 1 000°C) solid oxide fuel cell (SOFC)



Solid oxide electrolyte demands:

- High electrical conductivity for oxygen ions
- Low electrical conductivity for electrons
- Long-term stability for high-temperature operation
- Tightness for the non-ionized gases
- Chemical stability in contact with electrode materials and working gases
- Reliability, ageing resistance, thermal cyclability

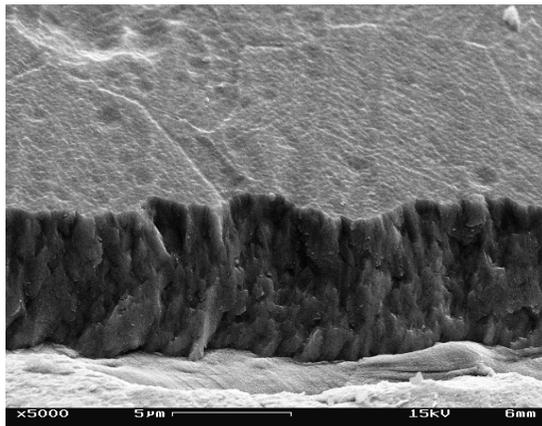
Graphics: Forschungszentrum Jülich GmbH,
Institut für Energieforschung

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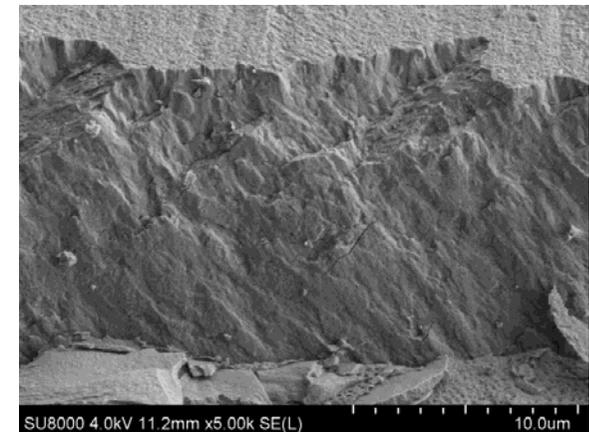
6 Application: Zirconium oxide coatings for fuel cells

Results:

- Strong influence of plasma activation on the microstructure
- Cubic phase with (111), (100) or (311) texture
- Additional effect on microstructure caused by pulsed bias
- Dense coatings, barrier properties for gases are promising
- High-rate PVD processes are available for dense YSZ



HAD process from ceramic
Electron beam power: 15 kW
Deposition rate: 40 nm/s
Pulsed Bias: - 120 V
Yttrium content: 5.2 at-%



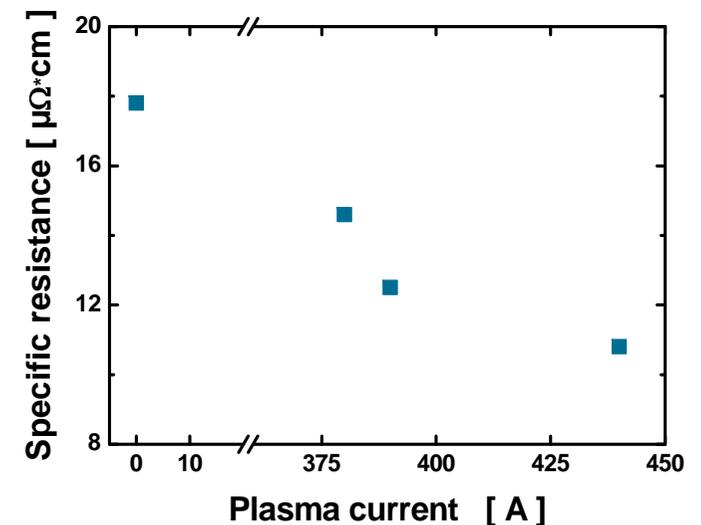
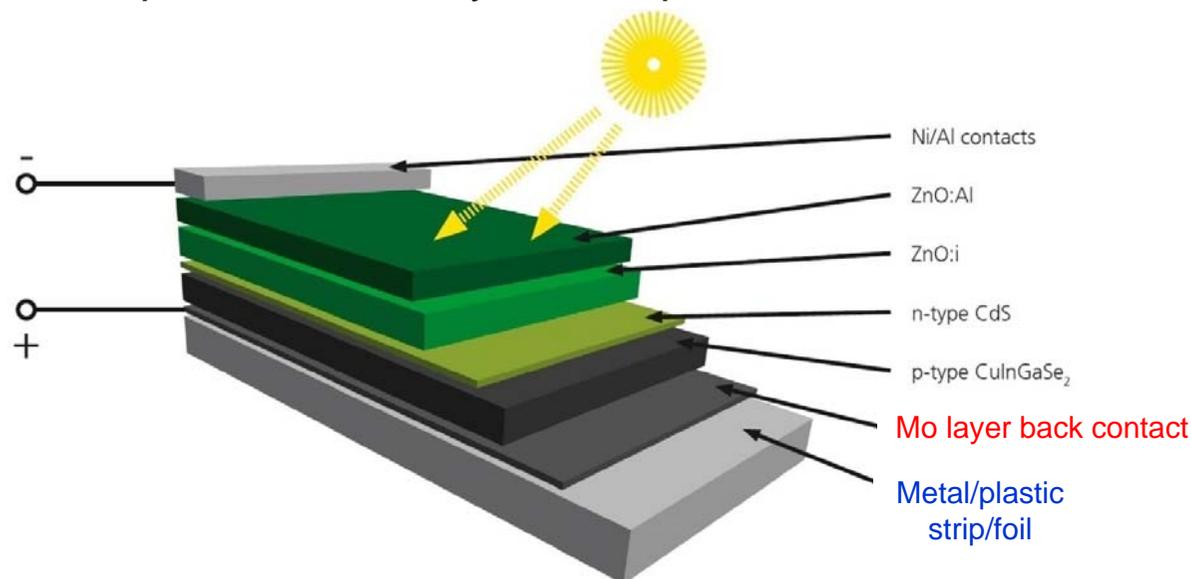
SAD process from metals
Electron beam power: 32 kW
Deposition rate: 30 nm/s
Pulsed Bias: - 120 V
Yttrium content: 5.4 at-%

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6 Application: Mo layers for photo voltaic application

Application:

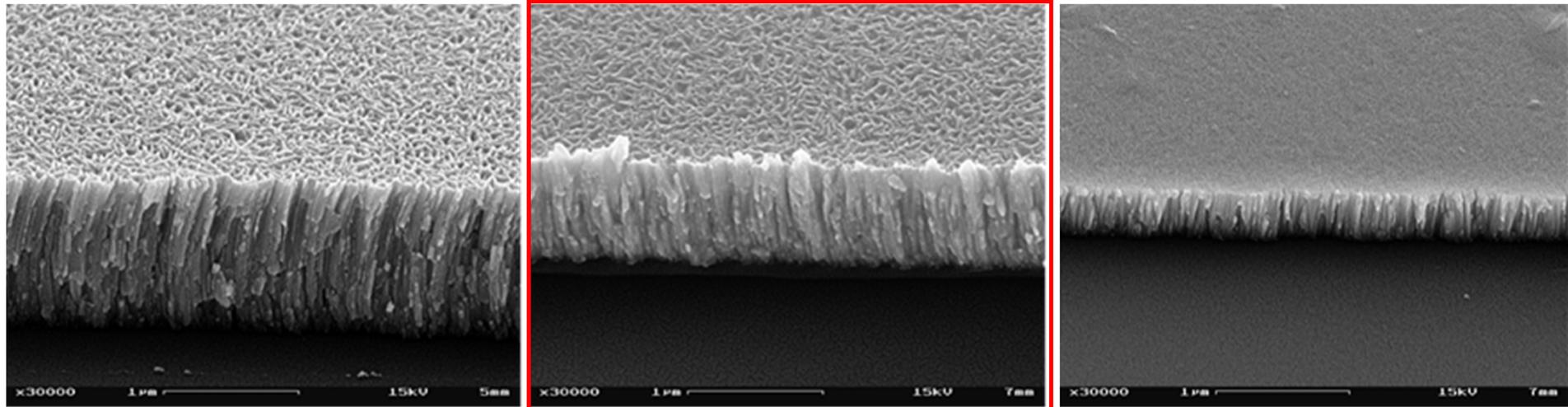
- Electrical back contact for CIS-/CIGS solar cells
- Molybdenum coatings guarantee therefore the needed chemical stability, the barrier against diffusion of impurities into the absorbing layer and the low ohmic resistance
- During processing of CIS-/CIGS solar cells temperatures of 500 – 600°C are needed
- Deposition of Mo layers with plasma activated electron beam evaporation (SAD process)



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6 Application: Mo layers for photo voltaic application

SEM pictures of different molybdenum layers, deposited by various PVD methods



Electron beam evaporation
without plasma activation
(rates up to 240 nm/s were
investigated)

Electron beam evaporation with
plasma activation (SAD process)
(actually rates up to 60 nm/s
were investigated,
higher rates possible)

Magnetron sputtering
(reference)
(typical rate 7 nm/s)

The deposited molybdenum layers on low sodium content glasses show the identical cell efficiency like standard layers.

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6 Application: Decorative coloured coatings

- Self coloured coatings like TiN
- Corrosion, abrasion and scratch protection
- High deposition rates up to 50 nm/s
- Dense layer structure by plasma activated deposition
- Typical layer thickness about 1.5 μm



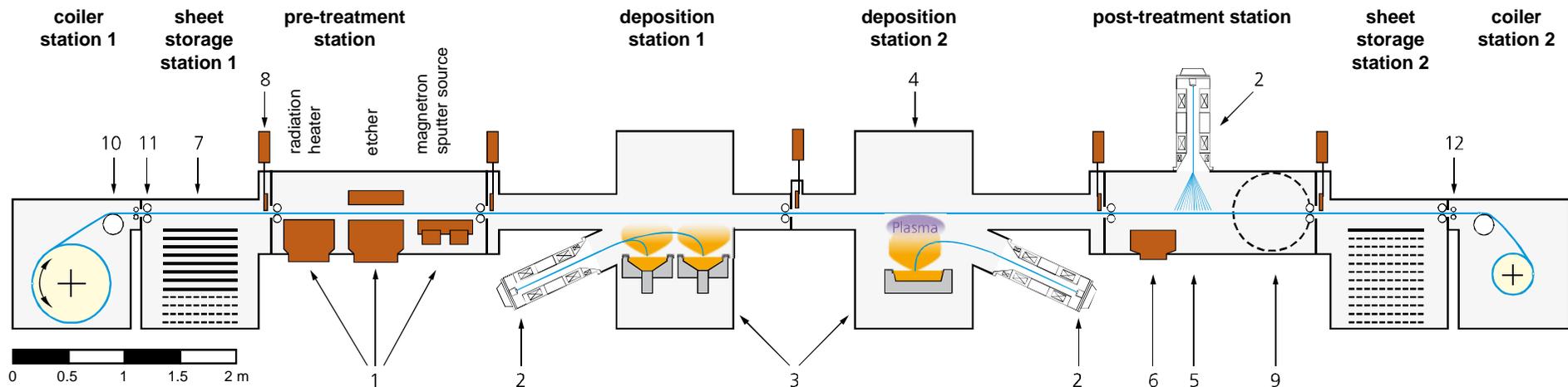
6 Application: Decorative coloured coatings

- Interference layers, transparent oxide layers based on TiO_2 , Cr_2O_3 , ZrO_2 , ...
- Hard coatings
- Corrosion, abrasion and scratch protection
- High deposition rates up to 3 nm/s
- High layer thickness uniformity ($< \pm 1.5\%$)
- Dense layer structure by pulsed magnetron sputtering
- Adjustable colour as a function of layer thickness
- Typical layer thickness 50 – 300 nm



7 FEP equipment - "MAXI"

In-line Vacuum Deposition Equipment for Sheets and Metal Strips



general

(flexible technological equipment - example)

- 1...various pre-treatment processes, e.g. heating, etching, deposition of interfacial layers
- 2...high power electron beam gun
- 3...various crucibles to evaporate different materials (metals, alloys or compounds)
- 4...plasma activated deposition process
- 5...thermal post-treatment, e.g. electron beam heating
- 6...XRF-thickness-distribution-measurement-system, optical film thickness measurement system by using acromatic light
- 7...sheets in frames, stacked
- 8...valves, to decouple pressure
- 9...turn-over device for double side coating of sheets
- 10...strip edge control system
- 11...sealing roll pairs, to decouple pressure
- 12...squeeze valve, during coil change

sheets

maximum size: 500 mm x 500 mm
 maximum weight: 15 kg
 speed: 0.001 ... 1.0 m/s

strips

maximum width: 300 mm
 minimum thickness: 0.04 mm
 maximum thickness: 1.50 mm
 speed: 0.001 ... 1.0 m/s



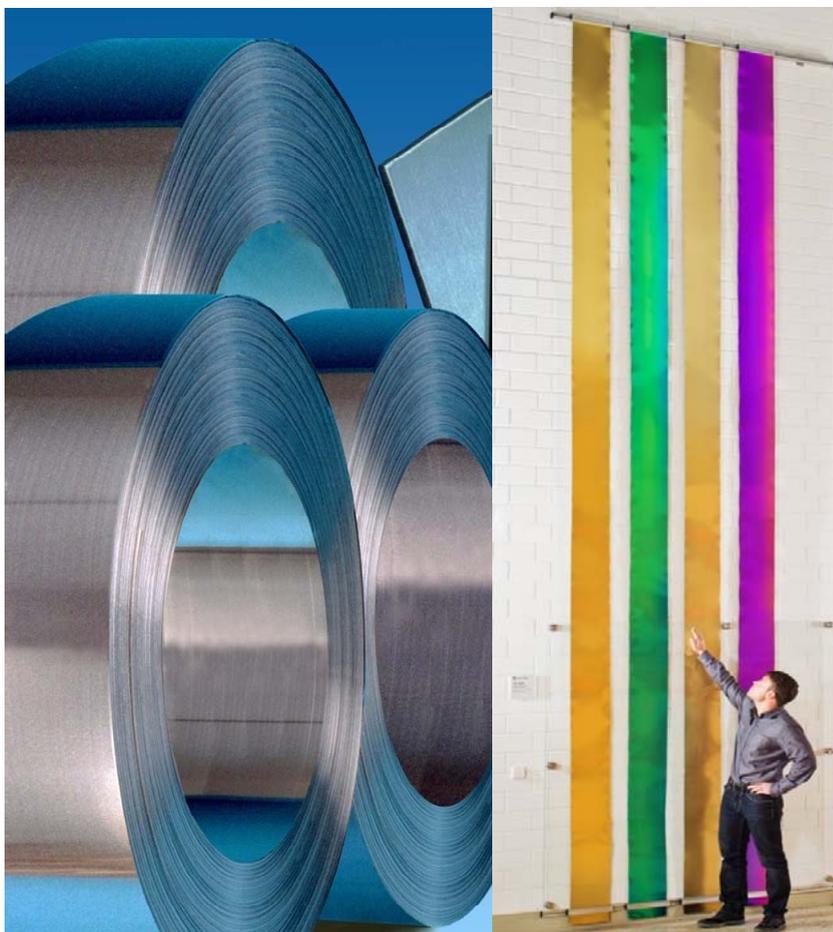
8 Summary and Outlook

New vacuum coating technologies for metal strips and foils

- Many new coating technologies are on the way
- New plasma processes are developed
- New cooling possibilities developed and proven
- Fundamental research has been performed
- Quality of the deposited layer stacks is promising
- Estimated deposition cost are reasonable
- Some unique large scale laboratory equipment are available at FEP
e.g. our MAXI line closes the gap between laboratory equipment and industrial plants
- Some new applications are well prepared for upscaling and industrialization
- Main fields of current and future applications:
Energy (PV, batteries, fuel cells, mirrors, solar thermal, ...) and decorative elements

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New vacuum coating technologies for metal strips and foils



Chr. Metzner, AIMCAL 2016

Ladies and gentlemen
thank you very much
for your kind attention!

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